EC-0011NCS

Features

Hi5.yHTMi(%ù Ni/C

FIP

-0011NCS is a kind of one-component high temperature curing Ni/C ally conductive adhesive. The material will build up strong adhesion fferent substrate after curing, which is suitable for FIP automatic ing applications.

Property	Typical Value	Unit	Test Method
	25	—	ASTM D2240
Viscosity @1s^{-1}	360	Pa.s	ASTM D2196 -
Density	1.68	g/cm^3	ASTM D792
T	0.7	MPa	ASTM D412
Elongation	200	%	ASTM D412
Cure Time	30-60@150°C	min	—
Temperature Range	-40 - 150	°C	—
Lap Shear Strength (Al/Al)	0.6	MPa	—
Volume Resistivity			
RoHS Compliance	YES	—	—
Shelf Life	6	month	-10°C

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.